HD74HC164

8-bit Parallel-out Shift Register

HITACHI

Description

This 8-bit shift register has gated serial inputs and clear. Each register bit is a D-type master/slave flip-flop. Inputs A & B permit complete control over the incoming data. A low at either or both inputs inhibits entry of new data and resets the first flip-vlop to the low level at the next clock pulse. A high level on the input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup and hold time requirements will be entered. Data is serially shifted in and out of the 8-bit register during the positive going transition of the clock pulse. Clear is independent of the clock and accomplished by a low level at the clear input.

Features

• High Speed Operation: t_{nd} (Clock to Q) = 14.5 ns typ ($C_L = 50 \text{ pF}$)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max

Function Table

Inputs				Outputs	;	
Clear	Clock	Α	В	Q _A	Q _B	 Q _H
L	Х	Х	Х	L	L	 L
Н	_	Х	Х	Q_{Ao}	Q_{Bo}	 Q _{Ho}
Н		L	Х	L	Q_{An}	 Q_{Gn}
Н		Х	L	L	Q_{An}	 Q_{Gn}
Н		Н	Н	Н	Q_{An}	 Q_Gn

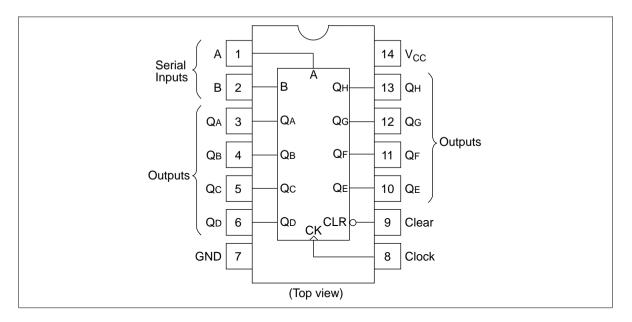
 Q_{Ao} to Q_{Ho} = Outputs remain unchanged.



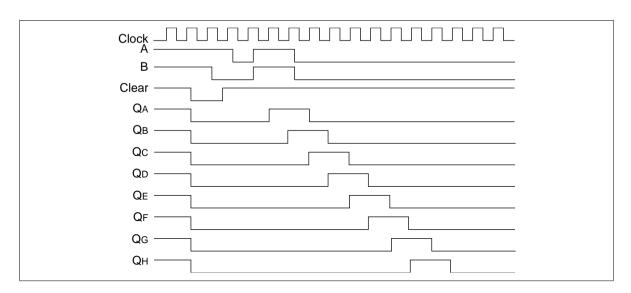
 Q_{An} to Q_{Gn} = Data shifted from the previous stage on a positive edge at the clock input.

HD74HC164

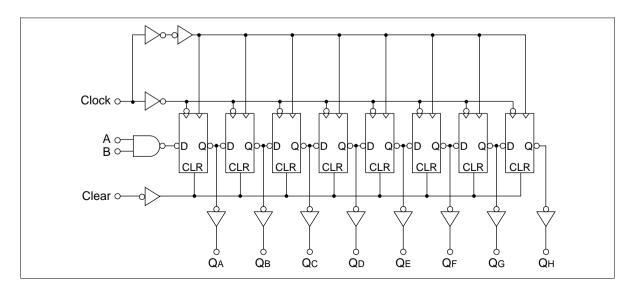
Pin Arrangement



Timing Diagram



Logic Diagram



HD74HC164

DC Characteristics

			Ta =	= 25°(Ta = - +85°C	-40 to			
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions	
Input voltage	V _{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	i —	_	3.15	_	=		
		6.0	4.2	_	_	4.2	_	=		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35	_		
		6.0	_	_	1.8	_	1.8	=		
Output voltage	V _{OH}	2.0	1.9	2.0		1.9	_	V	Vin = V_{IH} or V_{IL} $I_{OH} = -20 \mu$	ιΑ
		4.5	4.4	4.5	_	4.4	_	_		
		6.0	5.9	6.0	_	5.9	_	=		
		4.5	4.18	3 —		4.13	_	_	$I_{OH} = -4 \text{ m}.$	Α
		6.0	5.68	3 —	_	5.63	_	=	$I_{OH} = -5.2$	mA
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL} I_{OL} = 20 \mu A$	١
		4.5	_	0.0	0.1	_	0.1	_		
		6.0	_	0.0	0.1	_	0.1	_		
		4.5	_	_	0.26	_	0.33	=	$I_{OL} = 4 \text{ mA}$	
		6.0	_	_	0.26	_	0.33	_	$I_{OL} = 5.2 \text{ m}$	Α
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND	
Quiescent supply current	I _{cc}	6.0	_	_	4.0	_	40	μΑ	$Vin = V_{CC}$ or GND, lout = 0	μΑ

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

	Ta = -40 to
Ta = 25°C	+85°C

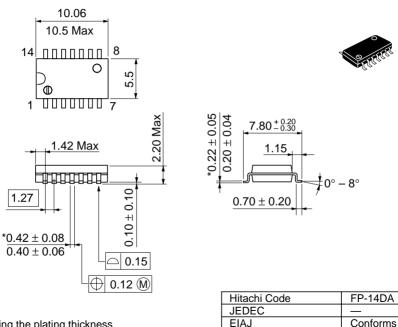
								_	
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	\mathbf{f}_{max}	2.0	_	_	5	_	4	MHz	
frequency		4.5	_	_	25	_	20		
		6.0	_	_	29	_	24	_	
Propagation delay	$t_{\tiny PHL}$	2.0	_	_	160	_	200	ns	Clock to Q
time		4.5	_	14	32	_	40	_	
		6.0	_	_	27	_	34	=	
	t _{PLH}	2.0	_	_	160	_	200	ns	_
		4.5	_	15	32	_	40	=	
		6.0	_	_	27	_	34	=	
	t _{PHL}	2.0	_	_	175	_	220	ns	Clear to Q
		4.5	_	17	35	_	44	_	
		6.0	_	_	30	_	37	_	
Setup time	t _{su}	2.0	100	_	_	125	_	ns	A, B to Clock
		4.5	20	1	_	25	_	=	
		6.0	17	_	_	21	_	=	
Hold time	t _h	2.0	5	_	_	5		ns	Clock to A, B
		4.5	5	0	_	5	_	_	
		6.0	5	_	_	5	_	_	
Removal time	t _{rem}	2.0	5	_	_	5	_	ns	Clear to Clock
		4.5	5	0	_	5	_	_	
		6.0	5	_	_	5	_	_	
Pulse width	t _w	2.0	80	_		100	_	ns	Clock
		4.5	16	8	_	20	_	_	
		6.0	14	_	_	17	_	_	
		2.0	80	_		100	_	ns	Clear
		4.5	16	5	_	20	_	=	
		6.0	14	_	_	17	_	_	
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns	
time	$t_{\scriptscriptstyle THL}$	4.5	_	5	15	_	19	_	
		6.0	_	_	13	_	16	_	
Input capacitance	Cin	_	_	5	10	—	10	pF	

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

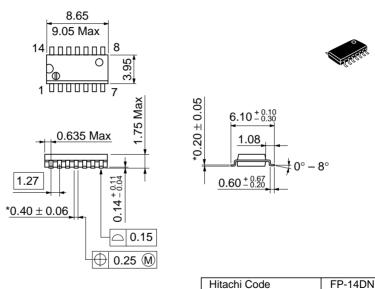


Weight (reference value)

0.23 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



JEDEC Conforms EIAJ Conforms Weight (reference value) 0.13 g

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